

Electron Beam Lithography System ELS-BODENS

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High Performance Capabilities for High Resolution and High Throughput Applications



ELS-BODENS
Acceleration 50 kV × Single Autoloader

Industry Fastest 400 MHz High Speed Scan

400MHz high-speed scan clock, 4 times faster than our conventional products. High current and narrow beam pitch, which was not possible until now. The ELS-BODENS achieves faster and higher exposure quality. It is ideal for MPWS (field-polymerized writing).

Faster Stage Speed

High-speed stage movement is crucial for exposures that require extensive stage movement, such as multiple fields and repeated detection of alignment marks. The redesigned stage of BODENS meets the demands of such production applications that throughputs are important.

Reduction of External Interference

Enclosure and EMI canceller are standard features, designed to reduce external interference of the environment and ensure a stable process.

Specifications

Electron Gun	ZrO/W Thermal Field Emitter				Max. Sample Size	8" Wafer
Acceleration Voltage	50 kV	100 kV	125 kV	150 kV	Max. Exposure Area	200 mm x 200 mm
Beam Current	1 nA ~ 800 nA	20 pA ~ 100 nA	5 pA ~ 100 nA	5 pA ~ 100 nA	Loading System	Single Autoloader Robot Loader
Min. Beam Spot Size	D 2.8 nm	D 1.8 nm	D 1.7 nm	D 1.5 nm		
Exposure Field Size	1000 μm □	1000 μm □	500 μm □	500 μm □	Software	elms • Beam Conditions • Exposure Schedule • Pattern Data Converter • Account Management • Python Scripting
Min. / Max. Field Size	Min. 100 μm □ Max. (Option) 3000 μm □					
Scan Clock	Max. 400 MHz					
Shot Pitch	Min. 0.2 nm					



